ENGINEERING INPUT - NEW CIRCUIT BOARD DESIGN			
TITLE		JOB NUM	
ELEC ENGINEER	EXT	CHG NUM	
MECH ENGINEER	EXT	SCHNUM	
PROJECT LEAD	EXT	BRD NUM	
DATE REC'D	CONTROL#	ASY NUM	
DATE REQ	QTY NEEDED	MECH NUM	

CHECKLIST	NOTES
PRELIMINARY:	
BOARD THICKNESS:	
COPPER THICKNESS:	
PROPOSED LAYER COUNT	
O BOARD OUTLINE: IMPORT FROM PRO/E	
O BOARD OUTLINE: INCLUDED IN FILES:	
O USE PREVIOUS PART NUM:	
☐ PRODUCTION OR ☐ TEST ONLY	
Y/N RECOMMENDED FLOOR PLAN	
SCHEMATIC: PLEASE INDICATE IF POSSIBLE	
☐ HIGH VOLTAGE / HIGH CURRENT	
☐ HIGH SPEED LINES / IMPEDANCE CONTROL	
☐ SIGNALS NEEDING SHIELDING OR ISOLATION	
☐ IF MULTIPLE GNDS, SHOW COMMON RETURN	
☐ ANY NET CLASSES, NET PROPERTIES IN SCH?	
☐ UNUSED INPUTS TIED HIGH OR LOW	
Y/N REORDER REFERENCE DESIGNATORS?	
LAYOUT CONSIDERATIONS:	
EXPLAIN IN NOTES (RIGHT COLUMN) OR ATTACH	
Y/N HIGH VOLUME? COST SENSITIVE?	
Y / N PALLETIZED FOR ASSEMBLY?	
Y/N COMPONENT HEIGHT RESTRICTIONS?	
Y/N COMPONENT KEEP-OUT AREAS?	
Y / N EXTRA TEST POINTS? ACCESSIBILITY?	
Y/N HEAT SINK REQUIREMENTS?	
Y / N ANY NEED FOR THERMAL ANALYSIS?	
Y / N ANY SIMULATION RESULTS (PSPICE)?	
Y/N EMC ANALYSIS?	
Y/N ORIENTATION EMULATORS/TEST/WAVE?	